

### **Dual N-channel MOSFET**

# KFC4B22830L Datasheet

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### **1. GENERAL DESCRIPTION**

Gate resistor installed Dual N-channel MOSFET for lithium-ion secondary battery protection circuits.

### 2. FEATURES

- Source-source On-state Resistance: RSS(on) typ = 55.5 m $\Omega$  (VGS = 3.8 V)
- CSP (Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1)

### 3. MARKING SYMBOL: T3

### 4. PACKAGING

Embossed type (Thermo-compression sealing): 20,000 pcs / reel (standard)

### 5. ABSOLUTE MAXIMUM RATINGS Ta = $25 \degree C$

Parameter		Symbol	Rating	Unit	
Source-source Voltage		VSS	20	V	
Gate-source Voltage		VGS	± 12	V	
Source Current	DC *1	IS1	2.3		
	DC *2	IS2	4.0	А	
	DC *3	IS3	4.9		
	Pulsed *4	ISp	23		
Total Power Dissipation	DC *1	PD1	0.34		
	DC *2	PD2	1.00	W	
	DC *3	PD3	1.50		
Operating Junction and Storage Temperature Range		Tj, Tstg	- 55 to + 150	°C	

### 6. THERMAL CHARACTERISTICS Ta = 25 °C

Parameter	Symbol	Rating	Unit
	Rth1 *1	368	
Thermal Resistance (ch-a)	Rth2 <sup>*2</sup>	125	°C / W
	Rth3 *3	84	

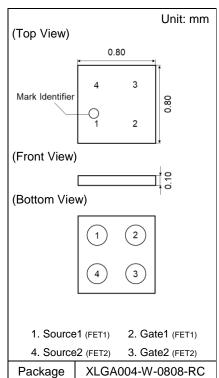
Note \*1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).

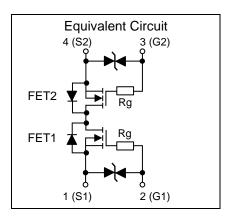
FR4 board partially covered with copper pad (19 mm<sup>2</sup> area, 36 µm thickness).
\*2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).

FR4 board fully covered with copper pad (615 mm<sup>2</sup> area, 36 µm thickness).

\*3 Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).

\*4 t = 10  $\mu s, \, Duty \, Cycle \leq$  1 %.



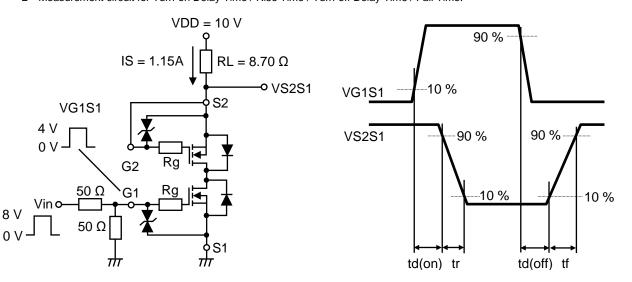


### 7. ELECTRICAL CHARACTERISTICS Ta = $25 \degree C \pm 3 \degree C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	20			V	
Zero Gate Voltage Source Current	ISSS	VSS = 20 V, VGS = 0 V			1	μA	
	IGSS1	$VGS = \pm 8 V, VSS = 0 V$			± 1	μA	
Gate-source Leakage Current	IGSS2	VGS = ± 3.8 V, VSS = 0 V			± 0.1		
Gate-source Threshold Voltage	Vth	IS = 0.07 mA, VSS = 10 V	0.35	0.90	1.40	V	
	RSS(on)1	IS = 1.15 A, VGS = 4.5 V	43.0	51.5	58.0		
Source course On state Registeres	RSS(on)2	IS = 1.15 A, VGS = 4.1 V	45.0	53.5	60.0		
Source-source On-state Resistance	RSS(on)3	IS = 1.15 A, VGS = 3.8 V	46.5	55.5	62.0	mΩ	
	RSS(on)4	IS = 1.15 A, VGS = 3.1 V	51.0	61.5	70.0		
Body Diode Forward Voltage	VF(s-s)	IF = 1.15 A, VGS = 0 V		0.8	1.0	V	
Input Capacitance *1	Ciss			230		pF	
Output Capacitance *1	Coss	S) IF = 1.15 A, VGS = 0 V VSS = 10 V, VGS = 0 V, f = 1 kHz		49			
Reverse Transfer Capacitance *1	Crss			39			
Turn-on Delay Time *1, *2	td(on)	VDD = 10 V, VGS = 0 to 4 V		0.08			
Rise Time <sup>*1, *2</sup>	tr	IS = 1.15 A		0.17		μs	
Turn-off Delay Time *1, *2	td(off)	VDD = 10 V, VGS = 4 to 0 V		0.42			
Fall Time <sup>*1, *2</sup>	tf	IS = 1.15 A		0.25		μs	
Total Gate Charge <sup>*1</sup>	Qg	VDD = 10 V		2.8			
Gate-source Charge *1	Qgs	VGS = 0 to 4 V		0.7		nC	
Gate-drain Charge *1	Qgd	Jd IS = 2.3 A		0.7			
Gate Resistance *1	Rg	f = 1 MHz	400	700	1000	Ω	

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors. \*1 Guaranteed by design, not subject to production testing.

\*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time.

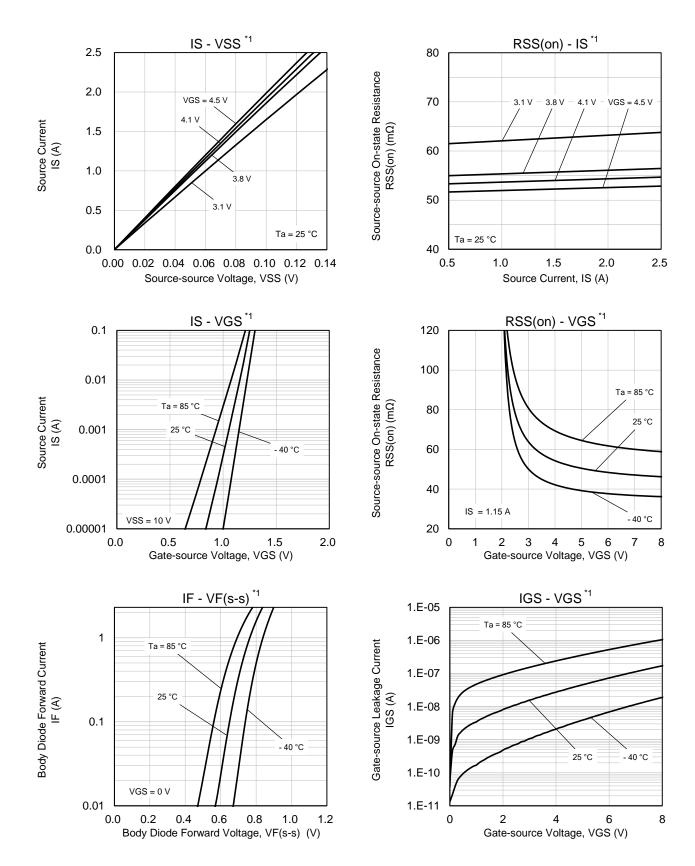


### 8. ELECTROSTATIC DISCHARGE CHARACTERISTIC Ta = 25 °C ± 3 °C

Standard	Test Type	Symbol	Conditions	Class	Value	Unit
AEC-Q101-001	Human Body Model	HBM	C = 100 pF, R = 1.5 kΩ	H1B	$> 0.5$ to $\leq 1$	kV

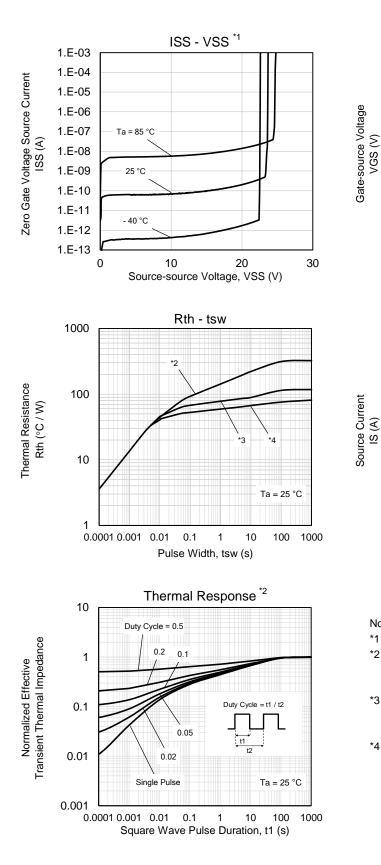
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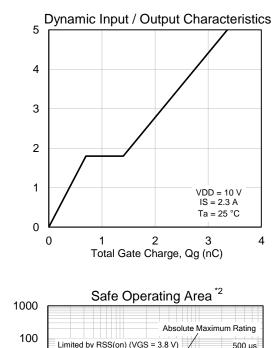
### 9. TECHNICAL DATA (Reference)

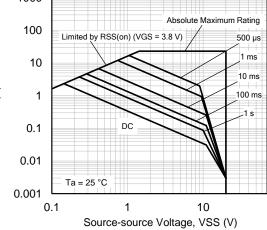


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### **TECHNICAL DATA (Reference)**







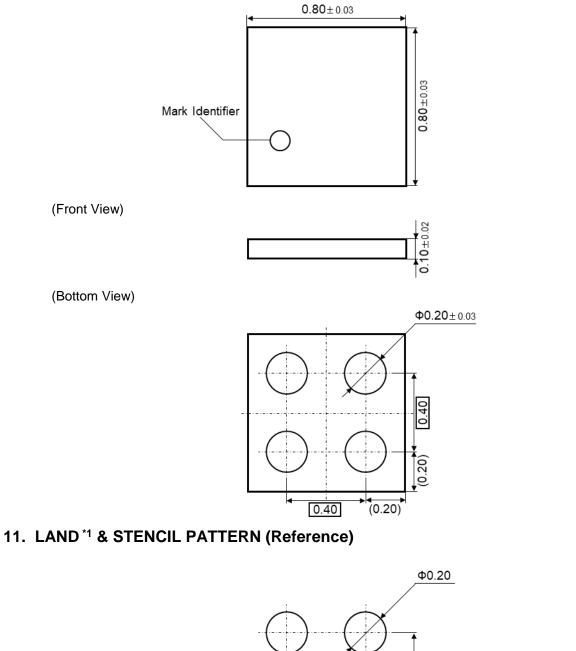
#### Note

- \*1 Pulse measurement.
- \*2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm). FR4 board partially covered with copper pad (19 mm<sup>2</sup> area, 36 μm thickness).
- \*3 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm). FR4 board fully covered with copper pad (615 mm<sup>2</sup> area, 36 μm thickness).
- \*4 Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).

Unit: mm

### 10. OUTLINE

(Top View)



Unit: mm

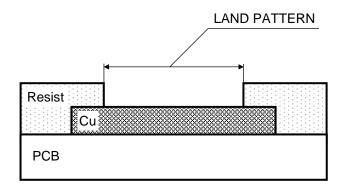
Note \*1 The definition of land pattern is referred to next page.

0.40

0.40



### **DEFINITION OF LAND PATTERN**



Important notice:

Solder Mask Defined (SMD) pattern is strongly recommended for pad design.

Please check the information in the Nuvoton WL-CSP Application Notes about mounting process.

### **12. REVISION HISTORY**

Date	Revision	Description	
2022.3.23	1.00	1. Initially issued.	

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